

APG22N15G

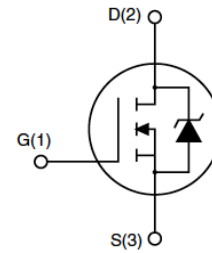
N-Channel Enhancement Mosfet

AIPOWER

DATA SHEET

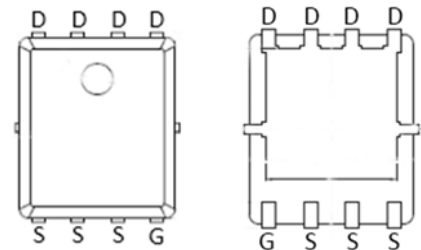
Features

- 150V,40A
 $R_{DS(ON)} < 22\text{ m}\Omega @ V_{GS}=10\text{V}$ TYP:19 m Ω
 $R_{DS(ON)} < 27\text{ m}\Omega @ V_{GS}=6\text{V}$ TYP:21m Ω
- Surface-mounted package
- Super Trench
- Low Thermal Resistance



Applications

- Motor drivers
- DC - DC Converter



PDFN5X6

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G22N15G	APG22N15G	PDFN5X6	-	-	5000

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_C=25^\circ\text{C}$) ⁽¹⁾	I_D	40	A
Continuous Drain Current ($T_C=100^\circ\text{C}$) ⁽¹⁾	I_D	16	A
Pulsed Drain Current ^(1,2)	I_{DM}	104	A
Single Pulsed Avalanche Energy ($V_{DD}=50\text{V}$, $L=1.0\text{mH}$)	E_{AS}	32	mJ
Drain Power Dissipation	P_D	35	W
Thermal Resistance from Junction to Case ⁽¹⁾	$R_{\theta JC}$	3.5	$^\circ\text{C}/\text{W}$
Thermal Resistance- Junction to Ambient ⁽¹⁾	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

Notes:

1. Surface Mounted on 1 in² pad area, $t \leq 10\text{ sec}$
2. Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
3. Limited by bonding wire

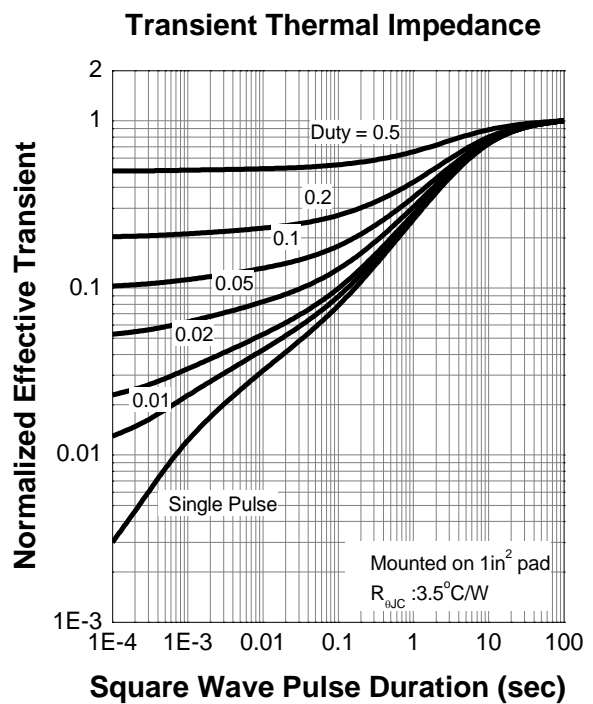
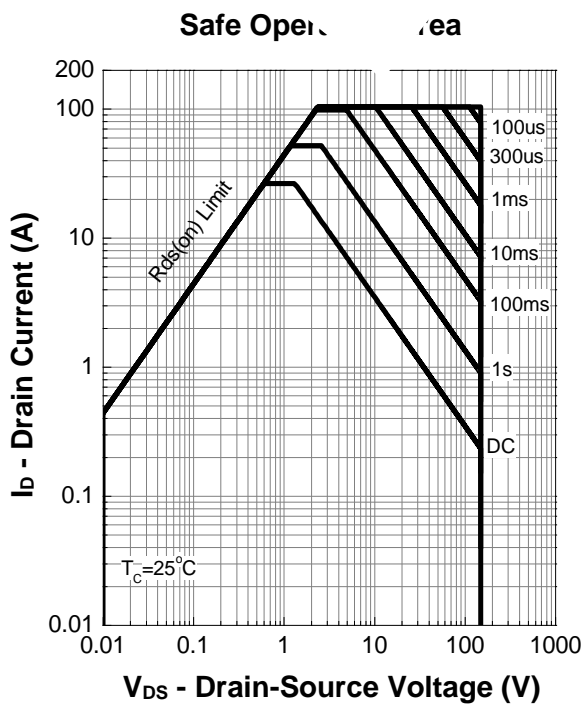
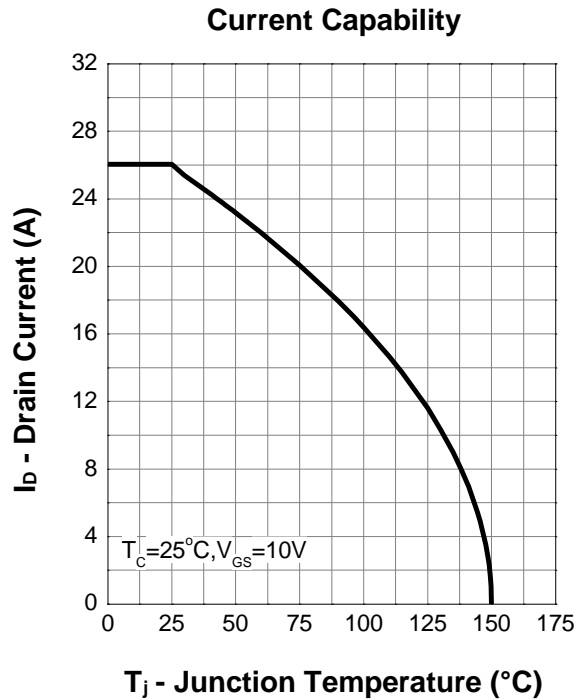
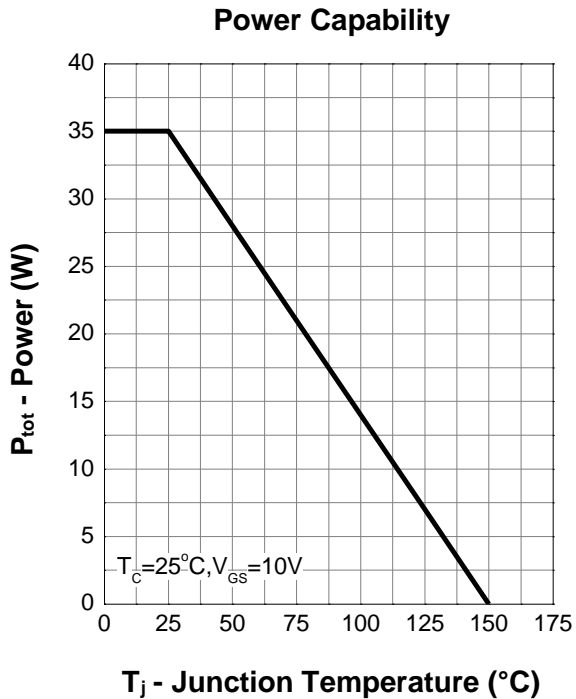
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	150	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =120V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	-	4.0	V
Drain-source on-resistance ^(a)	R _{DS(on)}	V _{GS} =10V, I _D =15A	-	19	22	mΩ
		V _{GS} =6V, I _D =10A	-	21	27	mΩ
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V, f =1.0MHz	-	2008	-	pF
Output Capacitance	C _{oss}		-	152	-	
Reverse Transfer Capacitance	C _{rss}		-	23	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} =75V, I _D =15A, R _G =3.9Ω, R _L =5Ω, V _G =10V	-	10	-	ns
Turn-on rise time	t _r		-	12	-	
Turn-off delay time	t _{d(off)}		-	25	-	
Turn-off fall time	t _f		-	11	-	
Total Gate Charge	Q _g	V _{DS} =75V, I _D =15A, V _{GS} =10V	-	35	-	nC
Gate-Source Charge	Q _{gs}		-	10	-	
Gate-Drain Charge	Q _{gd}		-	8	-	
Source-Drain Diode characteristics						
Diode Forward voltage ^(a)	V _{SD}	T _C =25°C, V _{GS} =0V, I _S =15A	-	-	1.3	V
Diode Forward current	I _S	T _C =25°C	-	-	40	A
Body Diode Reverse Recovery Time	t _{rr}	T _C =25°C, I _F =15A, di/dt=100A/us		72		ns
Body Diode Reverse Recovery Charge	Q _{rr}	T _C =25°C, I _F =15A, di/dt=100A/us		236		nc

Notes:

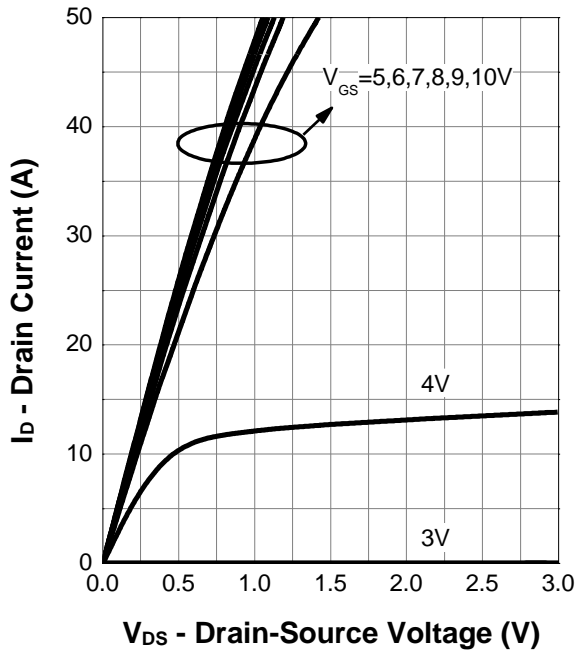
- a) : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2%
- b) : Guaranteed by design, not subject to production testing

Typical Characteristics (Cont.)

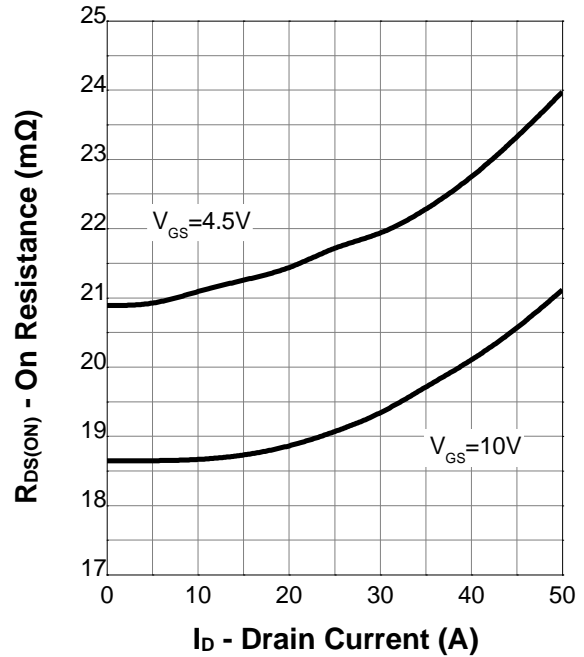


Typical Characteristics (Cont.)

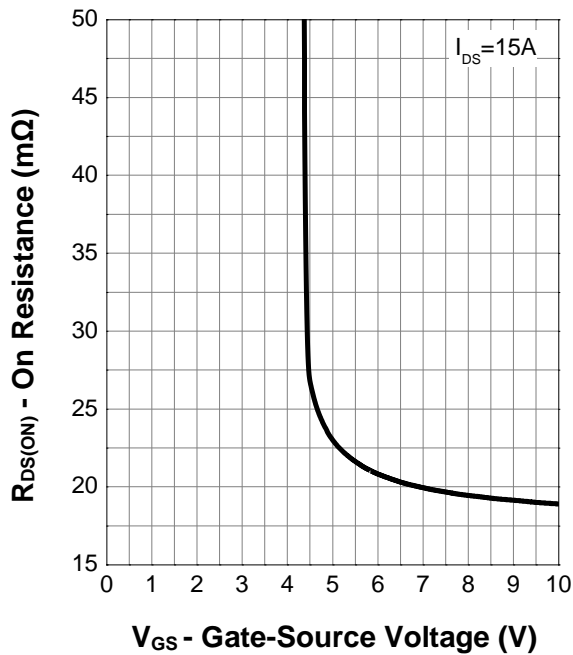
Output Characteristics



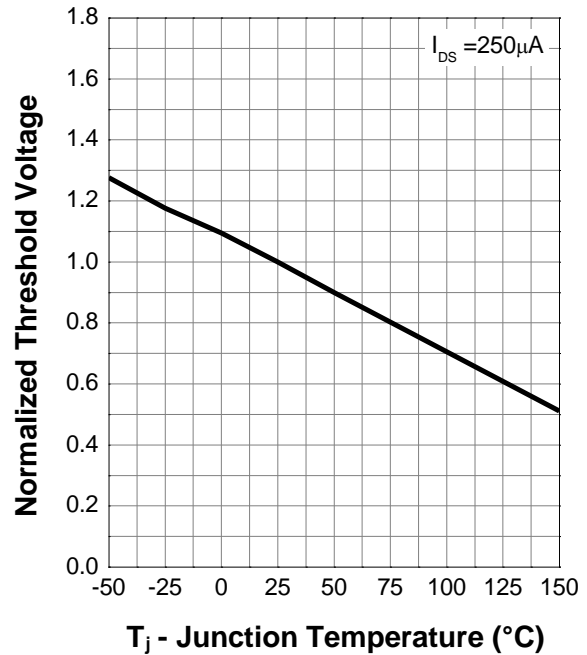
On Resistance



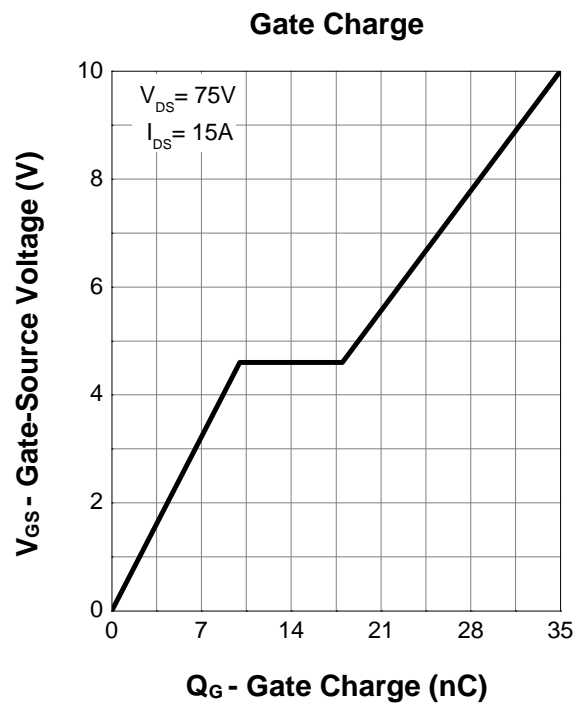
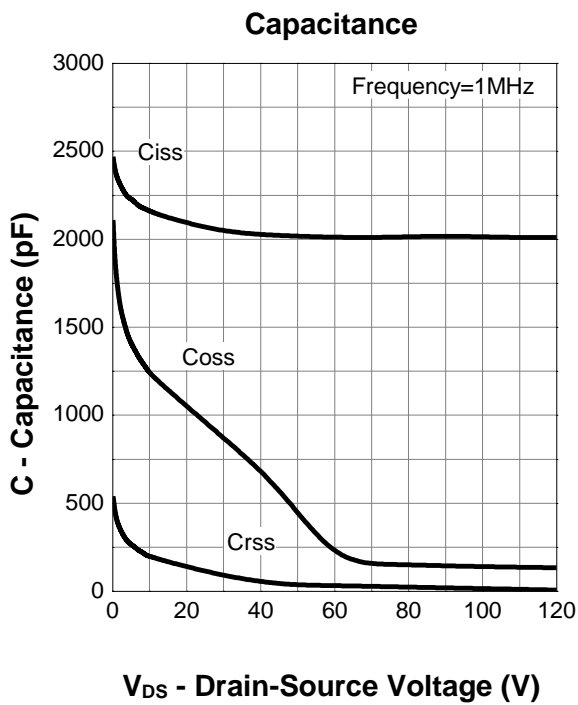
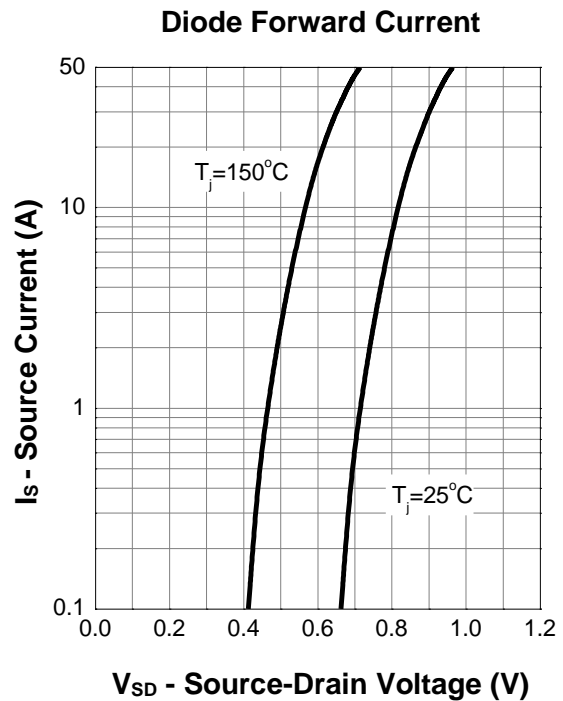
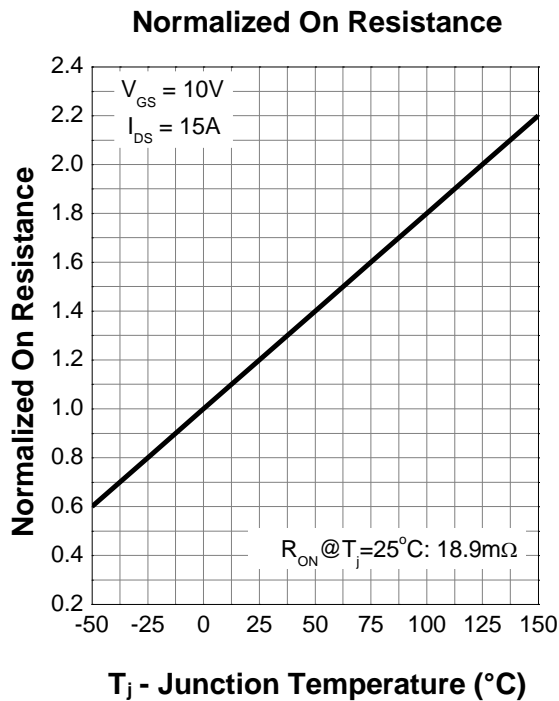
Transfer Characteristics



Normalized Threshold Voltage

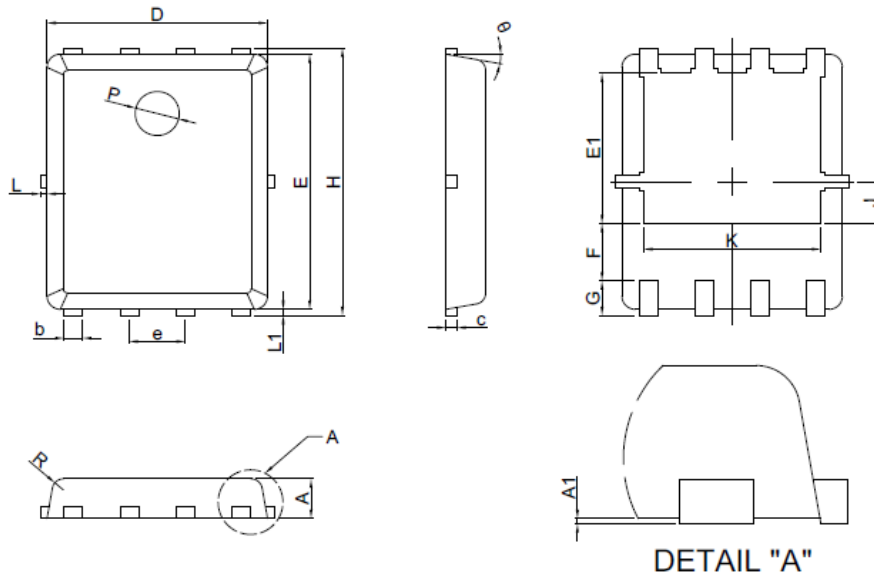


Typical Characteristics (Cont.)



Package Dimensions

PDFN5x6



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	0.80	1.00
A1	0.00	0.05
b	0.35	0.49
c	0.254REF	
D	4.90	5.10
F	1.40REF	
E	5.70	5.90
e	1.27BSC	
H	5.95	6.20
L1	0.10	0.18
G	0.60REF	
K	4.00REF	
L	-	0.15
J	0.95BSC	
P	1.00REF	
E1	3.40REF	
theta	6°	14°
R	0.25REF	